

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (currently amended) A process the for the preparation of a compound comprising at least two disulphide bonds from a precursor having at least two pairs of thiol groups, each pair of thiol groups being protected with different thiol-protecting groups selected from acetamidomethyl (Acm), 4-methylbenzyl (MBzl) and *t*-butyl (tBu), said process comprising:
  - (i) reaction of the precursor with an acid in the presence of an oxidising agent at a first temperature sufficient to effect deprotection of tBu protected thiols and disulphide bond formation for a first pair of protected thiol groups;
  - (ii) raising the temperature of the reaction mixture from step (i) to a second temperature sufficient to effect deprotection of Acm and /or MBzl protected thiols and disulphide bond formation for a second pair of protected thiol groups.
2. (previously presented) A process as claimed in claim 1 wherein said acid is trifluoroacetic acid (TFA).
3. (previously presented) A process as claimed in either one of claims 1 or 2 wherein said oxidising agent is dimethyl sulphoxide (DMSO).

4. (previously presented) A process as claimed in any one of claims 1 to 3 wherein deprotection is effected using a TFA/DMSO mixture comprising 1 to 20% DMSO.

5. (previously presented) A process as claimed in any one of claims 1 to 4 wherein said protected thiol is present in a peptide.

6. (previously presented) A process as claimed in claim 5 wherein said peptide comprises at least two tBu protected thiols and/or at least two Acn or MBzl protected thiols.

7. (previously presented) A process as claimed in any of claims 1 to 6 wherein tBu protected thiols are deprotected at room temperature in step (i).

8. (previously presented) A process as claimed in any one of claims 1 to 7 wherein Acn or MBzl protected thiols are deprotected at temperatures of 30-50°C, in step (ii).

9. (previously presented) A process as claimed in claim 8 wherein Acn or MBzl protected thiols are deprotected at temperatures of 50-70°C, in step (ii).